

# LECS2024 BELGIUM 5-6 December

#### GREENER ECS JOINING FORCES IN EUROPE Erika Györvary, Morgan Monroe 05.12.2024

# INCREASED USE OF ELECTRICAL COMPONENTS AND SYSTEMS (ECS)





# BY 2030, THE WORLDWIDE SEMICONDUCTORS (SC) INDUSTRY MANUFACTURING CAPACITY SHOULD NEARLY DOUBLE AS OF TODAY



EU Semicon capacity increase by factor of 4-5!

Emissions & waste & energy need increase accordingly!

Source: SIA, Applied Materials - SM



# **TWO PROBLEMS: EMISSIONS AND E-WASTE**

-

#### **Unsustainable Materials**



#### **Unsustainable Practices** Cause for Concern Amount of E-waste Generated and Collected Furope 17.6 7.53 342.8% Oceania 6.66 🗊 41.4% Americas 4.2 🗊 30% Asia 0.76 🗊 11.8% Africa 0.018 🗊 0.7% 10 15 **Global E-waste Global semiconductor** recycling rate: lifetime CO<sub>2</sub> footprint **≈ 22.3%** ≈ 500 Mt



E-waste values based on 2021 estimates as reported in the Global F-Waste Monitor 2024. In 2021 manufactured semiconductor devices lifetime CC Dipsiji in BCAeneos S 🕬 🔤 Inside

#### THE EUROPEAN CLIMATE LAW SETS AMBITIOUS GOALS:

#### A 55% REDUCTION IN GREENHOUSE GAS EMISSIONS BY 2030 AND CLIMATE NEUTRALITY BY 2050



EPoSS: ECS Sustainability & Environmental Footprint (<u>https://zenodo.org/records/11487615</u>)





# **SEMICONDUCTOR FAB EMISSIONS**

#### **COME MAINLY FROM PROCESS GASES AND ELECTRICITY CONSUMPTION** CO<sub>2</sub>-equivalent emissions for typical fab profile,<sup>1</sup>% share

Scope 3 upstream Scope 1 Scope 2 100 Other Facilities Other (including subfab) energy 80 Process gases Capital expenditures 60 A MID-SIZED Share Transport within Tools FOUNDRY USES scope Purchased raw material 40 and services 20 0 20 40 60 80 100 0 Share by scope

Excluding scope 3 downstream. Emissions averaged across 200-millimeter (mm) and 300-mm semiconductor fabs.

ABOUT AS MUCH ENERGY AS A TOWN OF 10,000 PEOPLE!





McKinsey

& Company

# **ENVIRONMENTAL IMPACT OF KEY PROCESS GASES**



Chipsjü

Aeneas 🚝 EPOSS.

Inside



# REDUCTION OF GREENHOUSE GASES VS IMPLEMENTATION COSTS



#### CHIPS JU 2024 Focus Topic







McKinsev

& Company

# UNDERSTANDING WHAT TO IMPROVE: LIFE-CYCLE ANALYSIS



Chipsjü

Aeneas 😚 Eposs.



#### SUSTAINABLE MANUFACTURING









#### 



#### SUSTAINABLE MANUFACTURING

Conventional/Greener Manufacturing

> 2.1 Printed sensors and circuits 2.3 Printed antennas for wireless power and communication 2.4 Printed energy harvesting and storage 2.5 Printed display

Image from Khan et al 2019

**Alternative** 

Manufacturing



Image from Fraunhofer ISC, CeSMA

Hybrid

**Electronics** 





# PATHS FOR IMPROVING SUSTAINABILITY OF ELECTRONICS

Eliminate noncritical components

> Eliminate bulky reader Switch comms & power to phone

Reduce and miniaturize

Simplify system to only essentials Minimize # of components

#### Switch to greener materials and methods

Switch to sustainable packaging Print antennas & sensors

Design for disassembly, reuse

Make reusable parts easy to recover and recycle

#### Design for disposability

ECS2024

Make non-reusable parts safe and easy to discard





 $m_{glucometer} = 60g$ 







SAMSUNG

# **HE& CHIPS JU PROJECTS ON SUSTAINABLE ECS**



Chipsjij

Aeneas 🦃



# **GREEN ELECTRONICS @ CHIPS JU**



#### SUSTRONICS

Circular electronic devices Sustainable manufacturing for electronics

> Environmentally compatible single-use electronics



Reduce, Reliability, Reuse, Repair, Refurbish, Recycle for zero e-waste. Wearable patches, Recyclable batterie, PCBs,...



#### GENESIS

Generate in EU a sustainable industry for semiconductors

Chipsjü

Aeneas 😤 Eposs.

6	Eco-friendly	Reduce E-waste	Green manufacturing
Ŷ	Eco-design, additive manufacturing, bio- based materials	Implementation of 6Rs for electronics design, Design for Disassembly	Materials, processes, monitoring, abatement
¢, ¢	Chips JU 2022	Chips JU 2022	Chips JU 2024
Ē	Ongoing	Ongoing	Starting



#### SUSTRONICS Sustainable and green electronics for circular economy

- 46 partners from 11 countries
- 30 industry partners throughout value chain
- 3 Years starting 1.6.2023
- <u>www.sustronics.eu</u>
- Coordinator: Philips, Technical manager: VTT

Ecosystem demonstrating how electronics industry can benefit from sustainability and circularity

3 use cases, 10 pilots, led by industry



Circular electronic devices

impact calculated

Status at M18



Sustainable

manufacturing for

electronics

• First prototypes of pilots integrated and their environmental



Environmentally compatible singleuse electronics

42% of consumers prefer <u>environmentally friendly</u> electronic devices, but 53% think there is a financial barrier<sup>1</sup>

SustrOnics

Chips<sub>JU</sub>

Environmental impact of <u>substrate</u> can decrease up to **75%** with sustainable alternatives<sup>2</sup>

- Development of circular business models on-going to support commercialisation
  New sustainable materials, processes, components and
- New sustainable materials, processes, components and devices available

<sup>1</sup>SUSTRONICS consumer study (1000 consumers from 5 countries)

<sup>2</sup>SUSTRONICS LCA calculations





# EECONE – EUROPEAN ECOSYSTEM FOR GREEN ELECTRONICS





- Over 50 partners
- 16 countries
- 3 years starting 01.07.2023
- Coordinator: Infineon



Guided by the 6R principles we develop the technology for a zero-waste future of electronic components and systems.



# GENESIS - GENERATE IN EUROPE A SUSTAINABLE INDUSTRY FOR SEMICONDUCTORS

#### ightarrow Improve the entire manufacturing sustainability chain value

Fab level : process & equipment

**GASES & CHEMICAL** 

(litho, bonding,

Low GWP gas (etch

eapt)

FFS2024

& clean)

PFAS free materials

- 60 partners from 12 countries
  - 32 industrial and 12 SME partners
  - 9 RTO and 7 academic partners
- 3 Years

Develop CRM

valorization solutions

recycling &

Coordinator: CEA-LETI Support: CSEM

2 💮 5 4 WASTE MONITORING & PROCESS **AIR EMISSIONS** FINAL TREATMENT TREATMENT Technology Reduce aqueous Reduce gas By-products & sustainable emission emission wastes sensing & alternatives Abatement Water abatement monitoring

H2 gas carrier re-

use (MOCVD)

**SubFab & facilities** 

- (FEOL- BEOL Packaging) Filtration and adsorption solutions
  - (PFAS...)
  - Reuse



Chipstii



#### **EPOSS WG GREEN ECS**







# **SELECT PROGRAM** SUSTAINABLE ELECTRONICS PROJECTS AT CSEM

#### **CSEM** internal

- EFORE ('23) & ENFRED ('24)
- SUMON ('23-'25)
- GREENPOCKET ('23) & COPPERFIELD ('24)

#### Swiss academic and industrial partners

- GREENSPACK (EMPA, EPFL)
- ELUSIVE (HEArC, Sonceboz)

#### **EU partners**

- SUSTRONICS
- EECONE
- TESLA

- $\rightarrow$  LCA of PCB and whole IoT device
- $\rightarrow$  Disposable AND sustainable
- $\rightarrow$  Feasibility of sustainable AM

- $\rightarrow$  Fully biodegradable alternatives
- $\rightarrow$  Triggerable PCB decomposition

- $\rightarrow$  Disposable and sustainable alternatives
- $\rightarrow$  Hybrid re-use / disposable alternatives
- $\rightarrow$  Fully biodegradable alternatives

# e csem

## FACING THE CHALLENGES OF OUR TIME

Dr. Erika Györvary Lead of EU Affairs Erika.Gyoervary@csem.ch